



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-30
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP25N80K5	R1DZ*VJ8LB52	A	3068	2017-01-30
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 5th August 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.64	Die / Leadframe	339
Lead	19.69	Softsolder	10364

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	RIDZ*VJ8L852					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	23.678	mg	supplier	die	Silicon (Si)	7440-21-3		22.547	mg	952234	11867
				supplier	metallization	Aluminium (Al)	7429-90-5		0.420	mg	17738	221
				supplier	metallization	Copper (Cu)	7440-50-8		0.155	mg	6546	82
				supplier	Passivation	Silicon Nitride	12033-89-5		0.097	mg	4097	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.240	mg	10136	126
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	465	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.154	mg	6504	81
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.054	mg	2281	28
Leadframe	Copper & its alloys	1253.535	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	998278	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	1000	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	300	198
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	391	258
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
Soft solder	Solder	20.619	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	19.691	mg	954993	10364
				supplier	solder	Silver (Ag)	7440-22-4		0.516	mg	25025	272
				supplier	solder	Tin (Sn)	7440-31-5		0.412	mg	19982	217
				supplier	wire	Aluminium (Al)	7429-90-5		0.146	mg	993197	77
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	6803	1
				supplier	Ribbon	Aluminium (Al)	7429-90-5		1.212	mg	1000000	638
Bonding Ribbons	Other Nonferrous metals & alloys	1.212	mg	supplier	Ribbon	Aluminium (Al)	7429-90-5		1.212	mg	1000000	638
				supplier	mold compound	Silica, vitreous	60676-86-0		517.169	mg	870000	272194
Encapsulation	Other Organic Materials	594.447	mg	supplier	mold compound	Epoxy resin	25068-38-6		59.445	mg	100001	31287
				supplier	mold compound	Phenol resin	29690-82-2		14.861	mg	25000	7822
				supplier	mold compound	Carbon Black	1333-86-4		2.972	mg	5000	1564
				supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348